Pressure sensors

C38 series

Series/Type: Absolute pressure sensor die for wet media
Ordering code: B58600E38**B650
Date: 2016-09-02
Version: 2
Applications

- Industrial
- Automotive
- Medical

Features

- Piezoresistive MEMS technology
- Small dimensions: 1.65 × 1.65 mm
- Square diaphragm
- Reference pressure chamber on top side
- Measured media (back side):
  - Non-aggressive gases and fluids. Unsuitable for substances which react with glass or silicon.
- Closed Wheatstone bridge with mV output, ratiometric to supply voltage
- Rated pressure range: 10 bar, 25 bar
- Outstanding high-long term stability

Delivery mode

- Tape

Dimensional drawings

[Image of dimensional drawings and circuit diagram]

All dimensions in µm.

Edge chipping max. 80 µm

Edge chipping max. 50 µm

Circuit diagram and connections:

Note 1: Diaphragm geometry depends on specification

Note 2: Without front side glass cap and without hole if front side absolute pressure sensor die

Recommended wire-bond area

Probe mark area

BOROFLOAT™ (optional)

(100) Silicon

Note 1: Diaphragm geometry depends on specification

Note 2: Without front side glass cap and without hole if front side absolute pressure sensor die

X1: Vout+
X2: VDD
X3: VDD
X4: Vout−
X5: VDD
X10: Substrate/Shield

BL SEN PS PD SD

2016-09-02
**Technical data**

### Absolute maximum ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply voltage</td>
<td>V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>Without damage&lt;sup&gt;1)&lt;/sup&gt;</td>
<td></td>
<td></td>
<td>10</td>
<td>V</td>
</tr>
<tr>
<td><strong>Temperature ranges</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating temperature range</td>
<td>T&lt;sub&gt;a&lt;/sub&gt;</td>
<td>2)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−40</td>
<td>135</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>For t &lt;15 min</td>
<td>−40</td>
<td>140</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature range</td>
<td>T&lt;sub&gt;st&lt;/sub&gt;</td>
<td>3)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−40</td>
<td>150</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td><strong>Pressure ranges</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating pressure ranges</td>
<td>p&lt;sub&gt;r&lt;/sub&gt;</td>
<td>Absolute pressure&lt;sup&gt;4)&lt;/sup&gt;</td>
<td>10</td>
<td>25</td>
<td></td>
<td>bar</td>
</tr>
<tr>
<td>Over pressure</td>
<td>p&lt;sub&gt;ov&lt;/sub&gt;</td>
<td>Absolute pressure&lt;sup&gt;5)&lt;/sup&gt;</td>
<td>3</td>
<td>25</td>
<td></td>
<td>p&lt;sub&gt;r&lt;/sub&gt;</td>
</tr>
<tr>
<td>Burst pressure</td>
<td>p&lt;sub&gt;burst&lt;/sub&gt;</td>
<td>Absolute pressure&lt;sup&gt;6)&lt;/sup&gt;</td>
<td>5</td>
<td>25</td>
<td></td>
<td>p&lt;sub&gt;r&lt;/sub&gt;</td>
</tr>
</tbody>
</table>

### Electrical specifications

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply voltage</td>
<td>V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>7)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>1.0</td>
<td>5.0</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Total bridge resistance</td>
<td>R&lt;sub&gt;S&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;8)&lt;/sup&gt;</td>
<td>3.4</td>
<td>4.0</td>
<td>4.6</td>
<td>kΩ</td>
</tr>
<tr>
<td>Temperature coefficient of total bridge resistance</td>
<td>α&lt;sub&gt;Rs&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;9)&lt;/sup&gt;</td>
<td>2.0</td>
<td>2.3</td>
<td>2.7</td>
<td>10&lt;sup&gt;−3&lt;/sup&gt;/K</td>
</tr>
<tr>
<td></td>
<td>β&lt;sub&gt;Rs&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;9)&lt;/sup&gt;</td>
<td>0</td>
<td>6</td>
<td>8</td>
<td>10&lt;sup&gt;−6&lt;/sup&gt;/K&lt;sup&gt;2&lt;/sup&gt;</td>
</tr>
<tr>
<td><strong>Output signal @ V&lt;sub&gt;DD&lt;/sub&gt; = 5 V</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Offset</td>
<td>V&lt;sub&gt;o&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;10)&lt;/sup&gt;</td>
<td></td>
<td></td>
<td>See next table</td>
<td>mV</td>
</tr>
<tr>
<td>Sensitivity</td>
<td>S</td>
<td>@ 25 °C&lt;sup&gt;11)&lt;/sup&gt;</td>
<td></td>
<td></td>
<td>See next table</td>
<td>mV/bar</td>
</tr>
<tr>
<td>Temperature coefficient of offset</td>
<td>TCV&lt;sub&gt;0&lt;/sub&gt;&lt;sup&gt;−&lt;/sup&gt; &amp; TCV&lt;sub&gt;0&lt;/sub&gt;&lt;sup&gt;+&lt;/sup&gt;</td>
<td>Unglued&lt;sup&gt;11)&lt;/sup&gt;</td>
<td></td>
<td>See next table</td>
<td>µV/VK</td>
<td></td>
</tr>
<tr>
<td></td>
<td>α&lt;sub&gt;S&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;15)&lt;/sup&gt;</td>
<td>−2.5</td>
<td>−2.2</td>
<td>−1.9</td>
<td>10&lt;sup&gt;−3&lt;/sup&gt;/K</td>
</tr>
<tr>
<td></td>
<td>β&lt;sub&gt;S&lt;/sub&gt;</td>
<td>@ 25 °C&lt;sup&gt;15)&lt;/sup&gt;</td>
<td>0</td>
<td>4</td>
<td>8</td>
<td>10&lt;sup&gt;−6&lt;/sup&gt;/K&lt;sup&gt;2&lt;/sup&gt;</td>
</tr>
<tr>
<td>Pressure hysteresis</td>
<td>pHys</td>
<td>16)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−0.1</td>
<td></td>
<td>0</td>
<td>1% FS</td>
</tr>
</tbody>
</table>

### Long-term stability (Full scale normal output FSON = 120 mV)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature hysteresis of offset</td>
<td>THV&lt;sub&gt;0&lt;/sub&gt;</td>
<td>17)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−0.2</td>
<td>±0.1</td>
<td>0.2</td>
<td>% FSON</td>
</tr>
<tr>
<td>Temperature cycle drift of offset</td>
<td>TCDV&lt;sub&gt;0&lt;/sub&gt;</td>
<td>17)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−0.1</td>
<td>±0.05</td>
<td>0.1</td>
<td>% FSON</td>
</tr>
<tr>
<td>High temperature drift of offset</td>
<td>HTDV&lt;sub&gt;0&lt;/sub&gt;</td>
<td>17)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−0.25</td>
<td>±0.05</td>
<td>0.25</td>
<td>% FSON</td>
</tr>
<tr>
<td>Long term stability of offset</td>
<td>LTSV&lt;sub&gt;0&lt;/sub&gt;</td>
<td>17)&lt;sup&gt;)&lt;/sup&gt;</td>
<td>−0.3</td>
<td>±0.1</td>
<td>0.3</td>
<td>% FSON</td>
</tr>
</tbody>
</table>
## Operating pressures and ordering codes

<table>
<thead>
<tr>
<th>Parameter @ 25 °C, $V_{DD} = 5$ V</th>
<th>Symbol</th>
<th>Typ.</th>
<th>Typ.</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating pressure 4) pr</td>
<td>$p_r$</td>
<td>10</td>
<td>25</td>
<td>bar</td>
</tr>
<tr>
<td>Offset voltage 10) [min/typ/max]</td>
<td>$V_o$</td>
<td>–8/–2/5</td>
<td>–7/–1/5</td>
<td>mV/V</td>
</tr>
<tr>
<td>Temperature coefficient of offset [min/typ/max]</td>
<td>$TCV_o^-$</td>
<td>-25/-10/5</td>
<td>-25/-10/5</td>
<td>μV/V/K</td>
</tr>
<tr>
<td></td>
<td>$TCV_o^+$</td>
<td>-15/-5/5</td>
<td>-15/-5/5</td>
<td>μV/V/K</td>
</tr>
<tr>
<td>Nonlinearity 14) [typ/max]</td>
<td>$L$</td>
<td>±0.2/±0.3</td>
<td>±0.2/±0.3</td>
<td>% FS</td>
</tr>
<tr>
<td>Sensitivity 13) [min/typ/max]</td>
<td>$S$</td>
<td>1.4/2/3.3</td>
<td>0.8/1/1.2</td>
<td>mV/V bar</td>
</tr>
<tr>
<td>Product type</td>
<td></td>
<td>AEA 10.00 C38/1 F04 G08 N</td>
<td></td>
<td></td>
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<tr>
<td>Ordering code</td>
<td></td>
<td>B58600E38**B650</td>
<td>B58600E38**B650</td>
<td></td>
</tr>
</tbody>
</table>

Other operating pressures upon request.
Symbols and Terms

1) **Maximum power supply VDD**
   This is the maximal allowed voltage, which may be applied to the piezoresistive bridge circuit without damage.

2) **Operating temperature range \( T_a \)**
   This is the operating Temperature range \( T_{a,\text{min}} \) to \( T_{a,\text{max}} \). Because most of the sensor parameters depend on assembling conditions like gluing, wire bonding etc, the die has to be tested over the operating temperature range by the customer fully assembled. For design verification and process control samples, mounted on TO39 base are tested over the temperature range of \( T_{\text{min}} \) to \( T_{\text{max}} \).

3) **Storage temperature range \( T_{st} \)**
   If the pressure sensor dies are stored in the temperature range \( T_{st,\text{min}} \) to \( T_{st,\text{max}} \) without applied voltage power supply, this will not affect the performance of the pressure sensor dies.

4) **Operating pressure range \( p_r \)**
   In the operating pressure range \( 0 \) to \( p_{r,max} \) the pressure sensor die output characteristic is as defined in this specification.

5) **Over pressure \( p_{ov} \)**
   Pressure cycles in the pressure range \( 0 \) to \( p_{ov} \) do not affect the performance of the pressure sensor dies.

6) **Burst pressure \( p_{berst} \)**
   Up to the burst pressure \( p_{berst} \) the diaphragm of the sensor die will not be destroyed mechanically. This parameter is tested at room temperature on samples mounted on an aluminium socket by increasing the applied pressure until the diaphragm is destroyed. Since the burst pressure depends on several assembling conditions, this parameter has to be verified by the customer with his assembling possibilities.

7) **Operating power supply VDD**
   The pressure sensor parameters are defined for a power supply voltage of \( VDD = 5 \text{ V} \). In the operating power supply voltage range \( V_{DD,\text{min}} \) to \( V_{DD,\text{max}} \) the ratiometric parameters \( r(VDD) \) like sensitivity, offset voltage and the temperature coefficient of the offset voltage are defined by:

   \[
   r(V_{DD}) = r(5[V]) \frac{V_{DD}}{5[V]}
   \]

8) **Total bridge resistance \( R_S \)**
   The total bridge resistance is defined between pad X5 and X2, (see the dimensional drawing in this data sheet) of the closed piezoresistive bridge circuit. The total bridge resistance is in a good approximation the output impedance of the piezoresistive bridge circuit. This parameter is tested completely on a wafer (wafer level test measurement).

9) **Temperature coefficients of resistance \( \alpha_{Rs} \) and \( \beta_{Rs} \):**
   The temperature coefficients of resistance are tested for design verification on samples, mounted on a TO39 base over the temperature range \( T_{\text{min}} \) to \( T_{\text{max}} \) with \( T_R = 25 \degree \text{C} \).
   The temperature coefficients of first and second order are defined with the polynomial:

   \[
   R_S(T) = R_S(T = 25 \degree \text{C}) \left[ 1 + \alpha_{Rs} \left( T - 25 \degree \text{C} \right) + \beta_{Rs} \left( T - 25 \degree \text{C} \right)^2 \right]
   \]
   The coefficients \( \alpha_{Rs} \) and \( \beta_{Rs} \) are calculated using the three measurement points of \( R_S(T) \) at \( T_{\text{meas, min}}, T_R \) and \( T_{\text{meas, max}} \).

10) **Offset voltage \( V_0 \)**
    The offset voltage \( V_0 \) is the output voltage \( V_{\text{out}}(p = 0 \text{ bar absolute}) \) at zero absolute pressure and for a bridge voltage power supply \( V_{DD} = 5 \text{ V} \). The high range of the allowed offset voltage is due to the reference pressure in the glass cap from 0 to 0.3 bar and to the tolerance of the sensitivity. The typical value of the reference pressure is 0.2 bar.
    Before anodic glass bonding the offset voltage is tested completely on a wafer (wafer level test measurement) with limits \(-25 \text{ mV} < V_0 < 25 \text{ mV} \). For design verification \( V_0 \) is measured on samples, mounted in AK transducer package (AK2 series) by extrapolating the output characteristic to zero bar.
    It should be noted that this parameter may be influenced by assembly.
11) **Temperature coefficient of offset voltage TCV₀**

The temperature coefficients of offset voltage are defined for a bridge voltage power supply $V_{DD} = 5 \text{ V}$. These parameters strongly depend on assembly conditions like gluing, wire bonding etc.

The temperature coefficients of offset voltage are tested for design verification on samples, mounted on AK transducer package (AK2 series) over a temperature range $T_{min}$ to $T_{max}$ with $T_R = 25 °C$.

$TCV₀^+ = \frac{V_o(T_{max}) - V_o(25°C)}{T_{max} - 25°C}$

$TCV₀^- = \frac{V_o(T_{min}) - V_o(25°C)}{T_{min} - 25°C}$

12) **Full scale value FS**

$FS = V_{out}(p_{r,max}) - V_o$

13) **Sensitivity S**

The sensitivity is defined for a bridge voltage power supply $V_{DD} = 5 \text{ V}$. It can be determined by the formula:

$S = \frac{V_{out}(p_{r,max}) - V_o}{p_{r,max}}$

This parameter is tested for process control on samples, mounted on a TO39 base.

14) **Nonlinearity L**

This parameter may be influenced by assembly.

The nonlinearity is measured using the endpoint method. Assuming a characteristic, this can be approximated by a polynomial of second order, where the maximum is at $p_x = p_{r,max}/2$. The nonlinearity is defined at $p_x = p_{r,max}/2$, using the equation:

$L = \frac{V_{out}(p_x) - V_o}{V_{out}(p_{r,max}) - V_o} - \frac{p_x}{p_{r,max}}$

This parameter is tested for process control on samples, mounted on a TO39 base.

15) **Temperature coefficient of sensitivity $α_Ś$ and $β_Ś$**

These parameters may be influenced by assembly.

The temperature coefficients of sensitivity are tested for design verification on samples, mounted on a TO39 base over the temperature range $T_{min}$ to $T_{max}$ with $T_R = 25 °C$.

The temperature coefficients of first and second order are defined with the polynomial:

$S(T) = S(T = 25 °C) \left[ 1 + α_Ś(T - 25 °C) + β_Ś(\frac{T - 25 °C}{2})^2 \right]$

The coefficients $α_Ś$ and $β_Ś$ are calculated using the three measurement points of $S(T)$ at $T_{meas,min}$, $T_R$ and $T_{meas,max}$.

16) **Pressure hysteresis pHys**

The pressure hysteresis is the difference between output voltages at constant pressure and constant temperature while applying a pressure cycle with pressure steps of $p_{r,min}$, $p_1$, $p_2$, $p_3$, $p_{r,max}$, $p_3$, $p_2$, $p_1$, $p_{r,min}$:

$pHys = \frac{V_{out,2}(p_k) - V_{out,1}(p_k)}{FS}$

With $k = min, 1, 2, 3, max$. The pressure steps are: $p_{min} = 0$, $p_1 = 0.25p_{r,max}$, $p_2 = 0.5p_{r,max}$, $p_3 = 0.75p_{r,max}$, $p_{r,max}$. This parameter is tested for design verification on samples, mounted on a TO39 base. Since the pHys depends on several assembling conditions, this parameter has to be verified by the customer with his assembling possibilities.

17) **Reliability data**

For long-term stability of offset voltage LTSV₀ please refer to the defined TDK standard AS100001 in chapter “Reliability data” on the internet. Since the LTSV₀ depends on several assembling conditions, this parameter has to be verified by the customer with his assembling possibilities.
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Cautions and warnings

Storage (general)
All pressure sensors should be stored in their original packaging. They should not be placed in harmful environments such as corrosive gases nor exposed to heat or direct sunlight, which may cause deformations. Similar effects may result from extreme storage temperatures and climatic conditions. Avoid storing the sensor dies in an environment where condensation may form or in a location exposed to corrosive gases, which will adversely affect their performance. Plastic materials should not be used for wrapping/packing when storing or transporting these dies, as they may become charged. Pressure sensor dies should be used soon after opening their seal and packaging.

Operation (general)
Media compatibility with the pressure sensors must be ensured to prevent their failure. The use of other media can cause damage and malfunction. Never use pressure sensors in atmospheres containing explosive liquids or gases.
Ensure pressure equalization to the environment, if gauge pressure sensors are used. Avoid operating the pressure sensors in an environment where condensation may form or in a location exposed to corrosive gases. These environments adversely affect their performance.
If the operating pressure is not within the rated pressure range, it may change the output characteristics. This may also happen with pressure sensor dies if an incorrect mounting method is used. Be sure that the applicable pressure does not exceed the overpressure, as it may damage the pressure sensor.
Do not exceed the maximum rated supply voltage nor the rated storage temperature range, as it may damage the pressure sensor.
Temperature variations in both the ambient conditions and the media (liquid or gas) can affect the accuracy of the output signal from the pressure sensors. Be sure to check the operating temperature range and thermal error specification of the pressure sensors to determine their suitability for the application.
Connections must be wired in accordance with the terminal assignment specified in the data sheets. Care should be taken as reversed pin connections can damage the pressure transmitters or degrade their performance. Contact between the pressure sensor terminals and metals or other materials may cause errors in the output characteristics.

Design notes (dies)
This specification describes the mechanical, electrical and physical requirements of a piezoresistive sensor die for measuring pressure. The specified parameters are valid for the pressure sensor die with pressure application either to the front or back side of the diaphragm as described in the data sheet. Pressure application to the other side may result in differing data. Most of the parameters are influenced by assembly conditions. Hence these parameters and the reliability have to be specified for each specific application and tested over its temperature range by the customer.

Handling/Mounting (dies)
Pressure sensor dies should be handled appropriately and not be touched with bare hands. They should only be picked up manually by the sides using tweezers. Their top surface should never be touched with tweezers. Latex gloves should not be used for handling them, as this will inhibit the curing of the adhesive used to bond the die to the carrier. When handling, be careful to avoid cuts...
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caused by the sharp-edged terminals. The sensor die must not be contaminated during manufacturing processes (gluing, soldering, silk-screen process).

The package of pressure sensor dies should not to be opened until the die is mounted and should be closed after use. The sensor die must not be cleaned. The sensor die must not be damaged during the assembly process (especially scratches on the diaphragm).

Storage conditions

Used materials for storage should be ESD protective according JESD625, non-outgassing, and chemically stable. Furthermore the following the following storage conditions should be preserved:

1. Storage in cabinets (if shipment package is opened):
   a. Atmosphere: inert gas, dry air or dry nitrogen
   b. Temperature range (in cabinet): 20±3 °C
   c. Relative humidity range (in cabinet): <40%
   d. Particle count (in cabinet): Class 6 per ISO 14644:1999 (equivalent FED STD 209E Class 1000)
   e. Shelf life under these conditions: 24 months for deliveries in trays
   f. Shelf life under these conditions: 12 months for deliveries on tape

2. Storage in containers (if shipment package is sealed):
   a. Sealed as delivered or backfilled with inert gas, dry air or dry nitrogen and re-sealed
   b. Temperature range: 20±3 °C
   c. Relative humidity range: <50%
   d. Particle count (during backfill): Class 6 per ISO 14644:1999 (equivalent FED STD 209E Class 1000)
   e. Shelf life under these conditions: 12 months for deliveries in trays
   f. Shelf life under these conditions: 6 months for deliveries on tape

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6. Unless otherwise agreed in individual contracts, **all orders are subject to our General Terms and Conditions of Supply.**

7. **Our manufacturing sites serving the automotive business apply the IATF 16949 standard.** The IATF certifications confirm our compliance with requirements regarding the quality management system in the automotive industry. Referring to customer requirements and customer specific requirements (“CSR”) TDK always has and will continue to have the policy of respecting individual agreements. Even if IATF 16949 may appear to support the acceptance of unilateral requirements, we hereby like to emphasize that only requirements mutually agreed upon can and will be implemented in our Quality Management System. For clarification purposes we like to point out that obligations from IATF 16949 shall only become legally binding if individually agreed upon.

8. The trade names **EPCOS, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, ExoCore, FilterCap, FormFit, LeaXield, MiniBlue, MiniCell, MKD, MKK, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, ThermoFuse, WindCap** are trademarks registered or pending in Europe and in other countries. Further information will be found on the Internet at www.tdk-electronics.tdk.com/trademarks.

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